

# 74LVC74A

Dual D-type flip-flop with set and reset; positive-edge trigger

Rev. 7 — 20 November 2012

Product data sheet

## 1. General description

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The 74LVC74A is a dual edge triggered D-type flip-flop with individual data ( $nD$ ) inputs, clock ( $nCP$ ) inputs, set ( $n\overline{SD}$ ) and ( $n\overline{RD}$ ) inputs, and complementary  $nQ$  and  $n\overline{Q}$  outputs.

The set and reset are asynchronous active LOW inputs and operate independently of the clock input. Information on the data input is transferred to the  $nQ$  output on the LOW-to-HIGH transition of the clock pulse. The  $nD$  inputs must be stable one set-up time prior to the LOW-to-HIGH clock transition, for predictable operation.

Schmitt trigger action at all inputs makes the circuit highly tolerant of slower input rise and fall times.

## 2. Features and benefits

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- 5 V tolerant inputs for interlacing with 5 V logic
- Wide supply voltage range from 1.2 V to 3.6 V
- CMOS low power consumption
- Direct interface with TTL levels
- Complies with JEDEC standard:
  - ◆ JESD8-7A (1.65 V to 1.95 V)
  - ◆ JESD8-5A (2.3 V to 2.7 V)
  - ◆ JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-B exceeds 200 V
  - ◆ CDM JESD22-C101E exceeds 1000 V
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$



### 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74LVC74AD	-40 °C to +125 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74LVC74ADB	-40 °C to +125 °C	SSOP14	plastic shrink small outline package; 14 leads; body width 5.3 mm	SOT337-1
74LVC74APW	-40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74LVC74ABQ	-40 °C to +125 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm	SOT762-1

### 4. Functional diagram

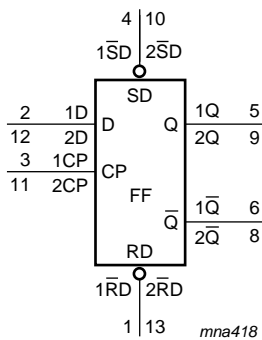


Fig 1. Logic symbol

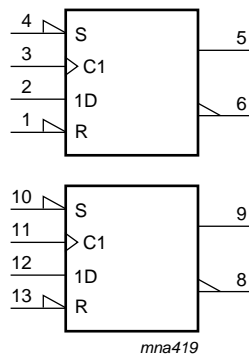


Fig 2. IEC logic symbol

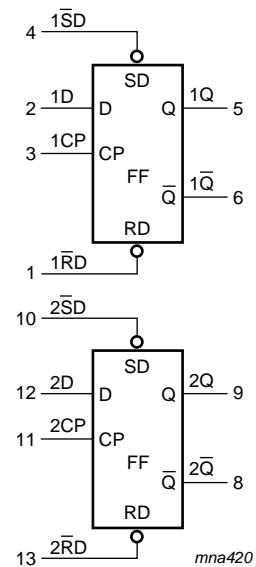


Fig 3. Functional diagram

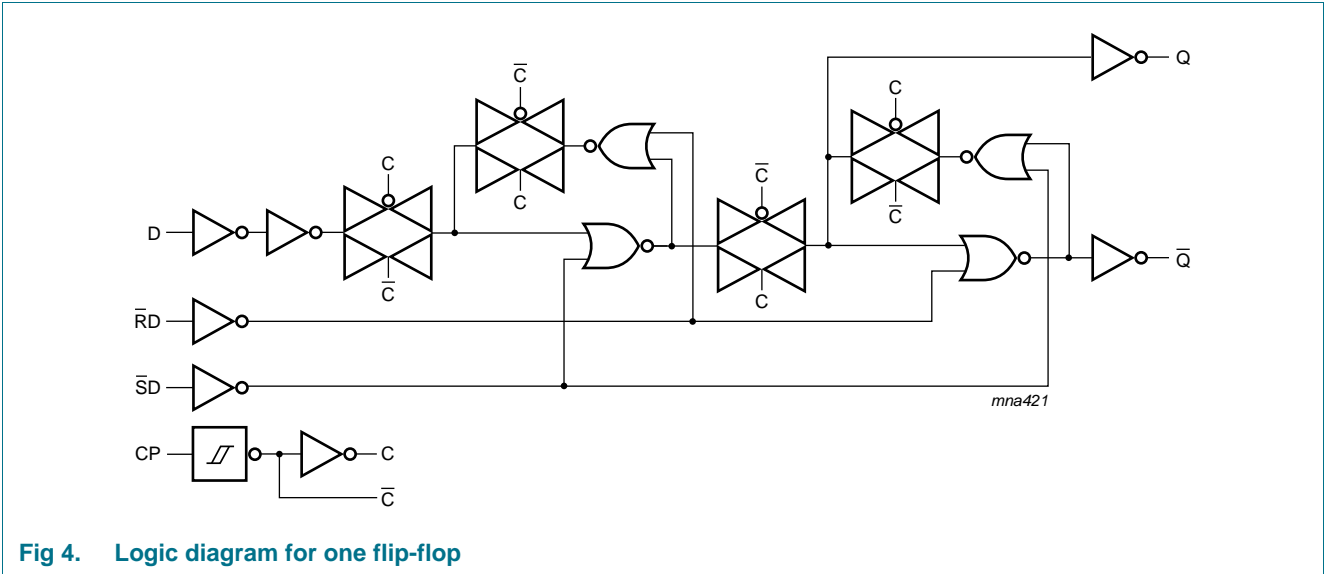


Fig 4. Logic diagram for one flip-flop

## 5. Pinning information

### 5.1 Pinning

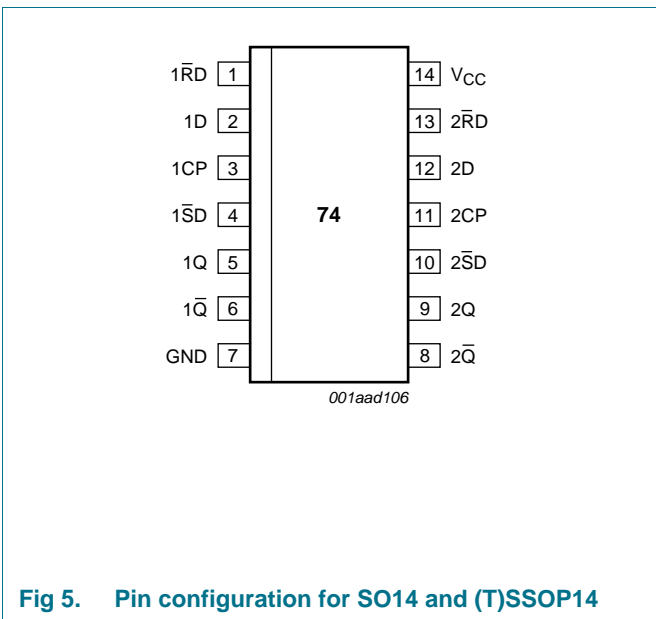


Fig 5. Pin configuration for SO14 and (T)SSOP14

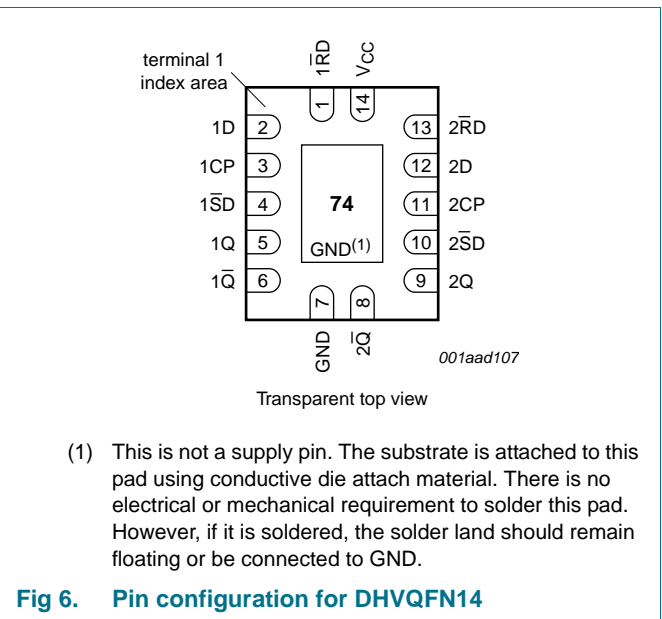


Fig 6. Pin configuration for DHVQFN14

## 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1 $\overline{\text{RD}}$	1	asynchronous reset-direct input (active LOW)
1D	2	data input
1CP	3	clock input (LOW-to-HIGH, edge-triggered)
1 $\overline{\text{SD}}$	4	asynchronous set-direct input (active LOW)
1Q	5	true output
1 $\overline{\text{Q}}$	6	complement output
GND	7	ground (0 V)
2 $\overline{\text{Q}}$	8	complement output
2Q	9	true output
2 $\overline{\text{SD}}$	10	asynchronous set-direct input (active LOW)
2CP	11	clock input (LOW-to-HIGH, edge-triggered)
2D	12	data input
2 $\overline{\text{RD}}$	13	asynchronous reset-direct input (active LOW)
V <sub>CC</sub>	14	supply voltage

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Input				Output	
n $\overline{\text{SD}}$	n $\overline{\text{RD}}$	nCP	nD	nQ	n $\overline{\text{Q}}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H	H

- [1] H = HIGH voltage level  
 L = LOW voltage level  
 X = don't care

Table 4. Function table<sup>[1]</sup>

Input				Output	
n $\overline{\text{SD}}$	n $\overline{\text{RD}}$	nCP	nD	nQ <sub>n+1</sub>	n $\overline{\text{Q}}$ <sub>n+1</sub>
H	H	↑	L	L	H
H	H	↑	H	H	L

- [1] H = HIGH voltage level  
 L = LOW voltage level  
 ↑ = LOW-to-HIGH transition  
 Q<sub>n+1</sub> = state after the next LOW-to-HIGH CP transition  
 X = don't care

## 7. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+6.5	V
$I_{IK}$	input clamping current	$V_I < 0$ V	-50	-	mA
$V_I$	input voltage		[1] -0.5	+6.5	V
$I_{OK}$	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	$\pm 50$	mA
$V_O$	output voltage		[2] -0.5	$V_{CC} + 0.5$	V
$I_O$	output current	$V_O = 0$ V to $V_{CC}$	-	$\pm 50$	mA
$I_{CC}$	supply current		-	100	mA
$I_{GND}$	ground current		-100	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C	[3] -	500	mW

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] For SO14 packages: above 70 °C the value of  $P_{tot}$  derates linearly with 8 mW/K.

For (T)SSOP14 packages: above 60 °C the value of  $P_{tot}$  derates linearly with 5.5 mW/K.

For DHVQFN14 packages: above 60 °C the value of  $P_{tot}$  derates linearly with 4.5 mW/K.

## 8. Recommended operating conditions

**Table 6. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage	for maximum speed performance	1.65	-	3.6	V
		for low-voltage applications	1.2	-	3.6	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 1.65$ V to 2.7 V	0	-	20	ns/V
		$V_{CC} = 2.7$ V to 3.6 V	0	-	10	ns/V

## 9. Static characteristics

**Table 7. Static characteristics**

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 1.2 V	1.08	-	-	1.08	-	V
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>	-	-	0.65 × V <sub>CC</sub>	-	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7	-	-	1.7	-	V
		V <sub>CC</sub> = 2.7 V to 3.6 V	2.0	-	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 1.2 V	-	-	0.12	-	0.12	V
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	-	0.35 × V <sub>CC</sub>	-	0.35 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	-	0.7	-	0.7	V
		V <sub>CC</sub> = 2.7 V to 3.6 V	-	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>						
		I <sub>O</sub> = -100 μA; V <sub>CC</sub> = 1.65 V to 3.6 V	V <sub>CC</sub> - 0.2	-	-	V <sub>CC</sub> - 0.3	-	V
		I <sub>O</sub> = -4 mA; V <sub>CC</sub> = 1.65 V	1.2	-	-	1.05	-	V
		I <sub>O</sub> = -8 mA; V <sub>CC</sub> = 2.3 V	1.8	-	-	1.65	-	V
		I <sub>O</sub> = -12 mA; V <sub>CC</sub> = 2.7 V	2.2	-	-	2.05	-	V
		I <sub>O</sub> = -18 mA; V <sub>CC</sub> = 3.0 V	2.4	-	-	2.25	-	V
		I <sub>O</sub> = -24 mA; V <sub>CC</sub> = 3.0 V	2.2	-	-	2.0	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>						
		I <sub>O</sub> = 100 μA; V <sub>CC</sub> = 1.65 V to 3.6 V	-	-	0.2	-	0.3	V
		I <sub>O</sub> = 4 mA; V <sub>CC</sub> = 1.65 V	-	-	0.45	-	0.65	V
		I <sub>O</sub> = 8 mA; V <sub>CC</sub> = 2.3 V	-	-	0.6	-	0.8	V
		I <sub>O</sub> = 12 mA; V <sub>CC</sub> = 2.7 V	-	-	0.4	-	0.6	V
		I <sub>O</sub> = 24 mA; V <sub>CC</sub> = 3.0 V	-	-	0.55	-	0.8	V
I <sub>I</sub>	input leakage current	V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = 5.5 V or GND	-	±0.1	±5	-	±20	μA
I <sub>CC</sub>	supply current	V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A	-	0.1	10	-	40	μA
ΔI <sub>CC</sub>	additional supply current	per input pin; V <sub>CC</sub> = 2.7 V to 3.6 V; V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A	-	5	500	-	5000	μA
C <sub>I</sub>	input capacitance	V <sub>CC</sub> = 0 V to 3.6 V; V <sub>I</sub> = GND to V <sub>CC</sub>	-	4.0	-	-	-	pF

[1] All typical values are measured at V<sub>CC</sub> = 3.3 V (unless stated otherwise) and T<sub>amb</sub> = 25 °C.

## 10. Dynamic characteristics

**Table 8. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
t <sub>pd</sub>	propagation delay	nCP to nQ, nQ̄; see <a href="#">Figure 7</a> <sup>[2]</sup>						
		V <sub>CC</sub> = 1.2 V	-	15	-	-	-	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.0	5.0	10.3	1.0	11.9	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.8	2.9	5.8	1.8	6.7	ns
		V <sub>CC</sub> = 2.7 V	1.0	2.7	6.0	1.0	7.5	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.0	2.6	5.2	1.0	6.5	ns
		nSD to nQ, nQ̄; see <a href="#">Figure 8</a>						
		V <sub>CC</sub> = 1.2 V	-	15	-	-	-	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.5	4.0	10.6	0.5	12.2	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.0	2.4	6.1	1.0	7.1	ns
		V <sub>CC</sub> = 2.7 V	1.0	2.9	6.4	1.0	8.0	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.0	2.2	5.4	1.0	7.0	ns
		nRD to nQ, nQ̄; see <a href="#">Figure 8</a>						
		V <sub>CC</sub> = 1.2 V	-	15	-	-	-	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.5	4.1	10.7	0.5	12.4	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.0	2.4	6.1	1.0	7.1	ns
		V <sub>CC</sub> = 2.7 V	1.0	3.0	6.4	1.0	8.0	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.0	2.2	5.4	1.0	7.0	ns
t <sub>w</sub>	pulse width	clock HIGH or LOW; see <a href="#">Figure 7</a>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	5.0	-	-	5.0	-	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	4.0	-	-	4.0	-	ns
		V <sub>CC</sub> = 2.7 V	3.3	-	-	4.5	-	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	3.3	1.3	-	4.5	-	ns
		set or reset LOW; see <a href="#">Figure 8</a>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	5.0	-	-	5.0	-	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	4.0	-	-	4.0	-	ns
		V <sub>CC</sub> = 2.7 V	3.3	-	-	4.5	-	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	3.3	1.7	-	4.5	-	ns
t <sub>rec</sub>	recovery time	set or reset; see <a href="#">Figure 8</a>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.5	-	-	1.5	-	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.5	-	-	1.5	-	ns
		V <sub>CC</sub> = 2.7 V	1.5	-	-	1.0	-	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	+1.0	-3.0	-	1.0	-	ns

**Table 8. Dynamic characteristics ...continued**

*Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 9](#).*

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
t <sub>su</sub>	set-up time	nD to nCP; see <a href="#">Figure 7</a>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	3.0	-	-	3.0	-	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	2.5	-	-	2.5	-	ns
		V <sub>CC</sub> = 2.7 V	2.2	-	-	2.2	-	ns
t <sub>h</sub>	hold time	nD to nCP; see <a href="#">Figure 7</a>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	2.0	-	-	2.0	-	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.5	-	-	1.5	-	ns
		V <sub>CC</sub> = 2.7 V	1.0	-	-	1.0	-	ns
f <sub>max</sub>	maximum frequency	nCP; see <a href="#">Figure 7</a>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	100	-	-	80	-	MHz
		V <sub>CC</sub> = 2.3 V to 2.7 V	125	-	-	100	-	MHz
		V <sub>CC</sub> = 2.7 V	150	-	-	120	-	MHz
t <sub>sk(o)</sub>	output skew time	V <sub>CC</sub> = 3.0 V to 3.6 V <a href="#">[3]</a>	-	-	1.0	-	1.5	ns
		C <sub>PD</sub>	per flip-flop; V <sub>I</sub> = GND to V <sub>CC</sub> <a href="#">[4]</a>					
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	12.4	-	-	-	pF
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	16.0	-	-	-	pF
C <sub>PD</sub>	power dissipation capacitance	V <sub>CC</sub> = 3.0 V to 3.6 V	-	19.1	-	-	-	pF

[1] Typical values are measured at T<sub>amb</sub> = 25 °C and V<sub>CC</sub> = 1.2 V, 1.8 V, 2.5 V, 2.7 V and 3.3 V respectively.

[2] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.

[3] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

[4] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f<sub>i</sub> = input frequency in MHz; f<sub>o</sub> = output frequency in MHz

C<sub>L</sub> = output load capacitance in pF

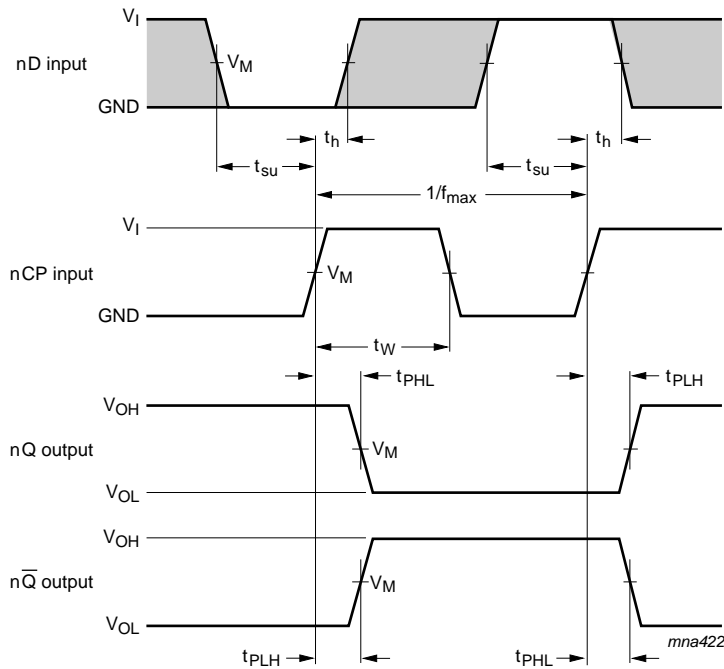
V<sub>CC</sub> = supply voltage in Volts

N = number of inputs switching

Σ(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of the outputs



11. AC waveforms

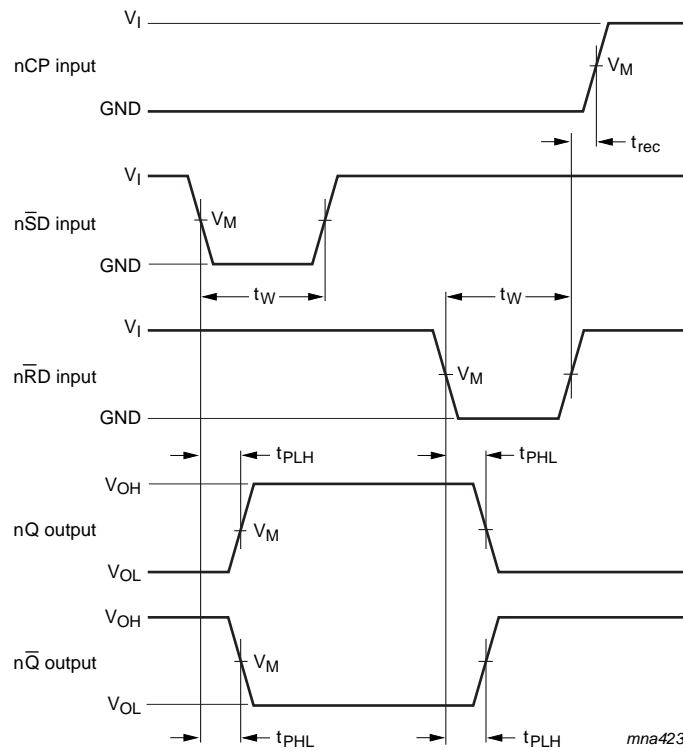


The shaded areas indicate when the input is permitted to change for predictable output performance.

Measurement points are given in [Table 9](#).

$V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 7. The clock input (nCP) to output (nQ, nQ-bar) propagation delays, the clock pulse width, the nD to nCP set-up, the nCP to nD hold times, and the maximum frequency**



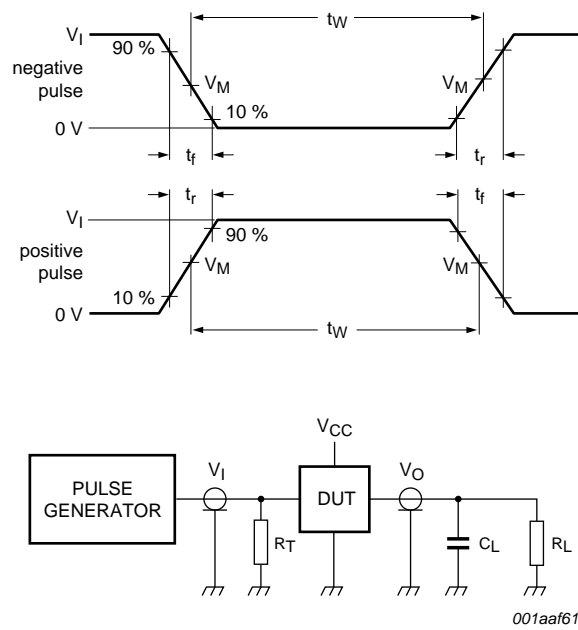
Measurement points are given in [Table 9](#).

$V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 8. The set ( $\overline{nSD}$ ) and reset ( $\overline{nRD}$ ) input to output ( $nQ$ ,  $\overline{nQ}$ ) propagation delays, the set and reset pulse widths, and the  $nRD$  to  $nCP$  recovery time**

**Table 9. Measurement points**

Supply voltage	Input		Output
$V_{CC}$	$V_I$	$V_M$	$V_M$
1.2 V	$V_{CC}$	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
1.65 V to 1.95 V	$V_{CC}$	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.3 V to 2.7 V	$V_{CC}$	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.7 V	2.7 V	1.5 V	1.5 V
3.0 V to 3.6 V	2.7 V	1.5 V	1.5 V



Test data is given in [Table 10](#).

Definitions for test circuit:

$R_L$  = Load resistance.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

**Fig 9. Load circuitry for switching times**

**Table 10. Test data**

Supply voltage	Input		Load		$V_{EXT}$		
$V_{CC}$	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PLH}, t_{PHL}$	$t_{PLZ}, t_{PZL}$	$t_{PHZ}, t_{PZH}$
1.2 V	$V_{CC}$	$\leq 2$ ns	30 pF	1 k $\Omega$	open	$2 \times V_{CC}$	GND
1.65 V to 1.95 V	$V_{CC}$	$\leq 2$ ns	30 pF	1 k $\Omega$	open	$2 \times V_{CC}$	GND
2.3 V to 2.7 V	$V_{CC}$	$\leq 2$ ns	30 pF	500 $\Omega$	open	$2 \times V_{CC}$	GND
2.7 V	2.7 V	$\leq 2.5$ ns	50 pF	500 $\Omega$	open	$2 \times V_{CC}$	GND
3.0 V to 3.6 V	2.7 V	$\leq 2.5$ ns	50 pF	500 $\Omega$	open	$2 \times V_{CC}$	GND

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

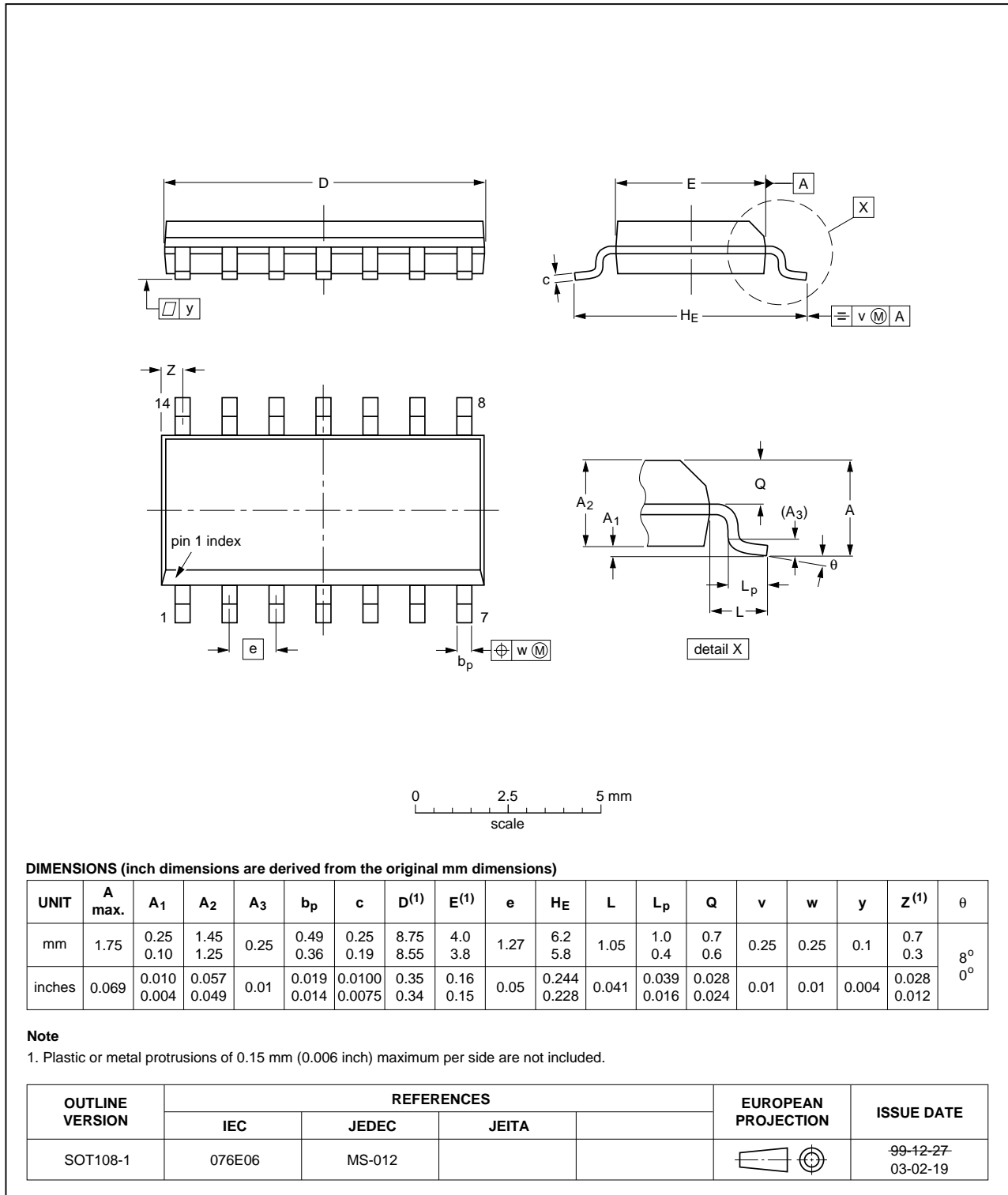


Fig 10. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

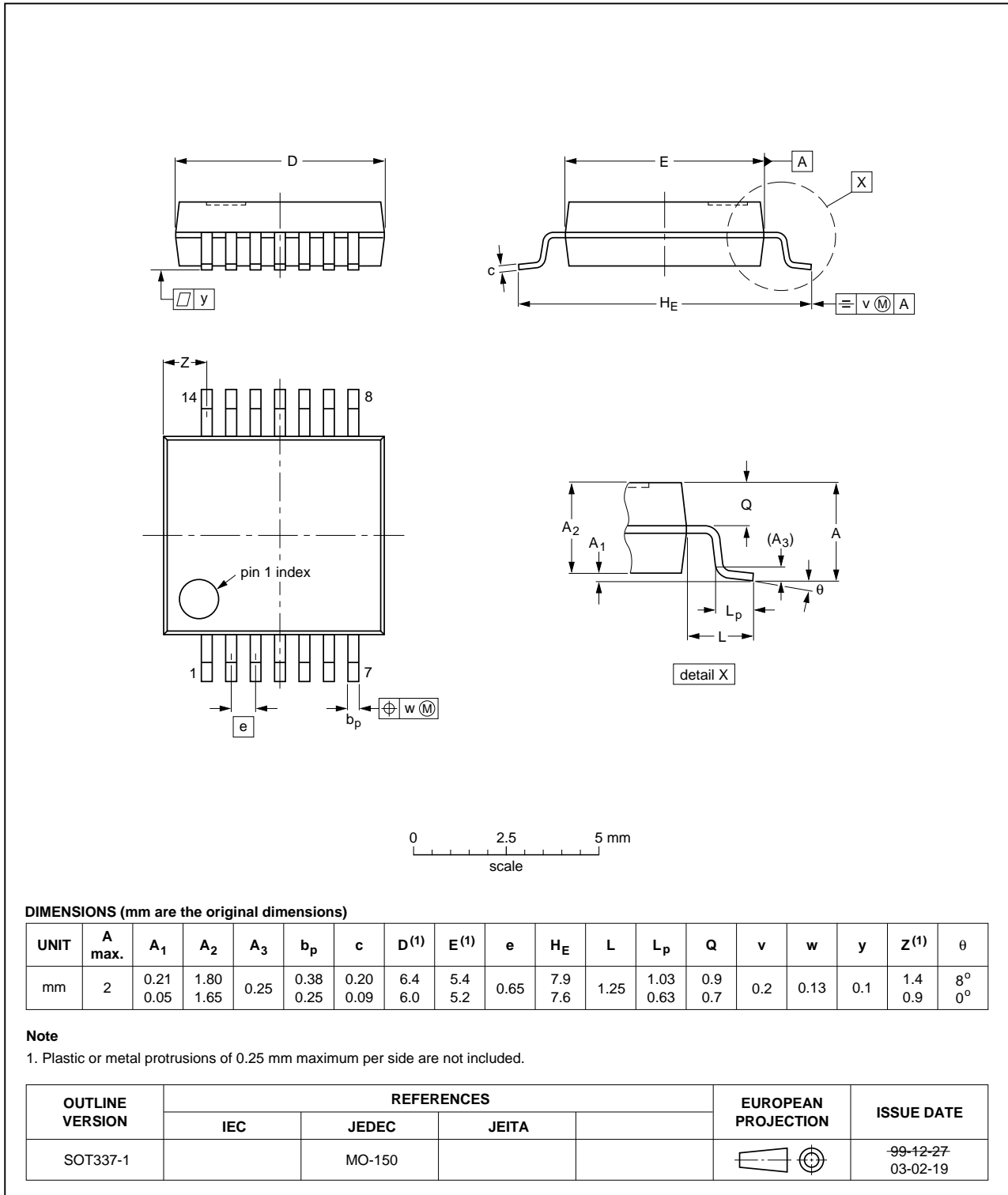


Fig 11. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

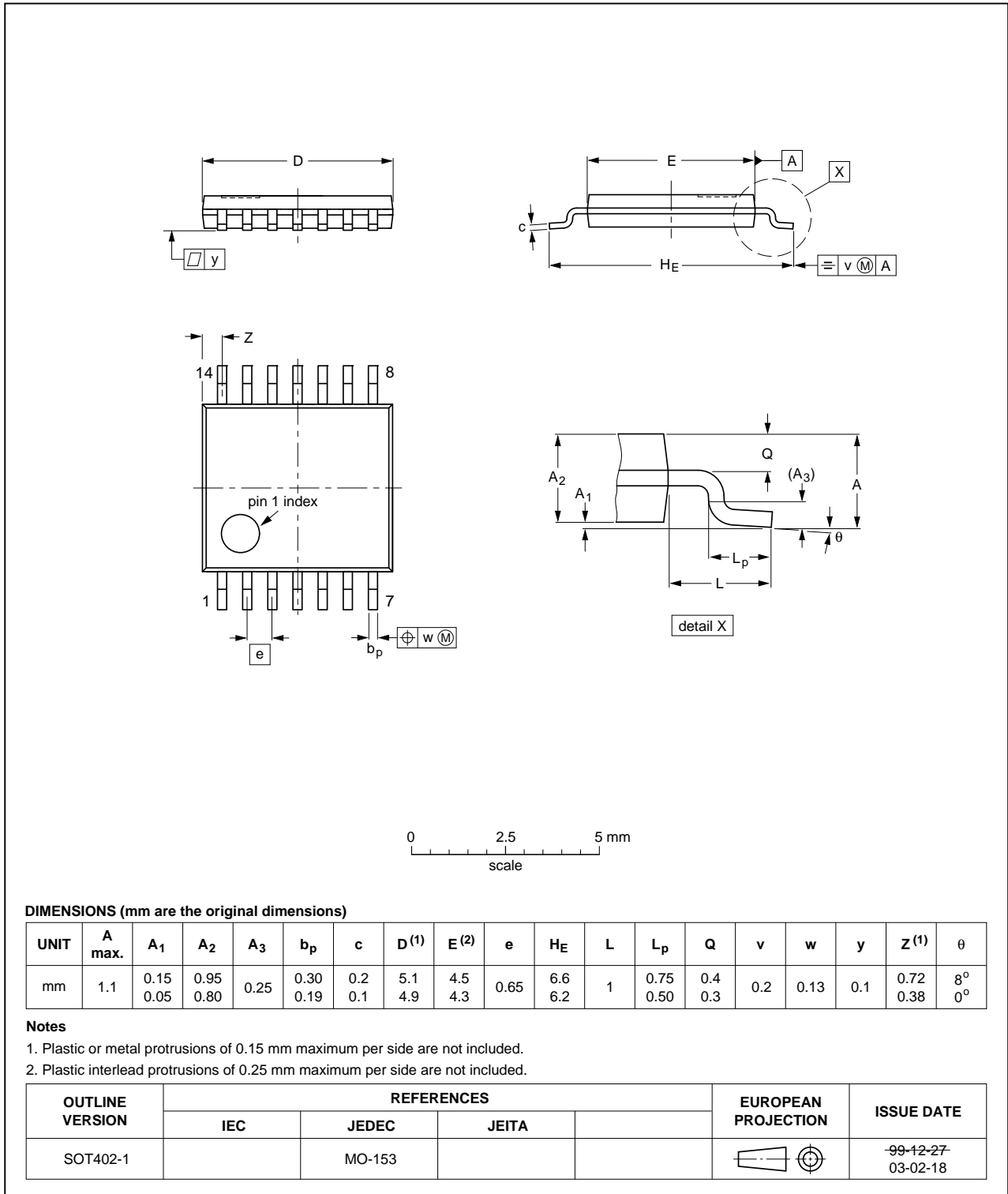


Fig 12. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1

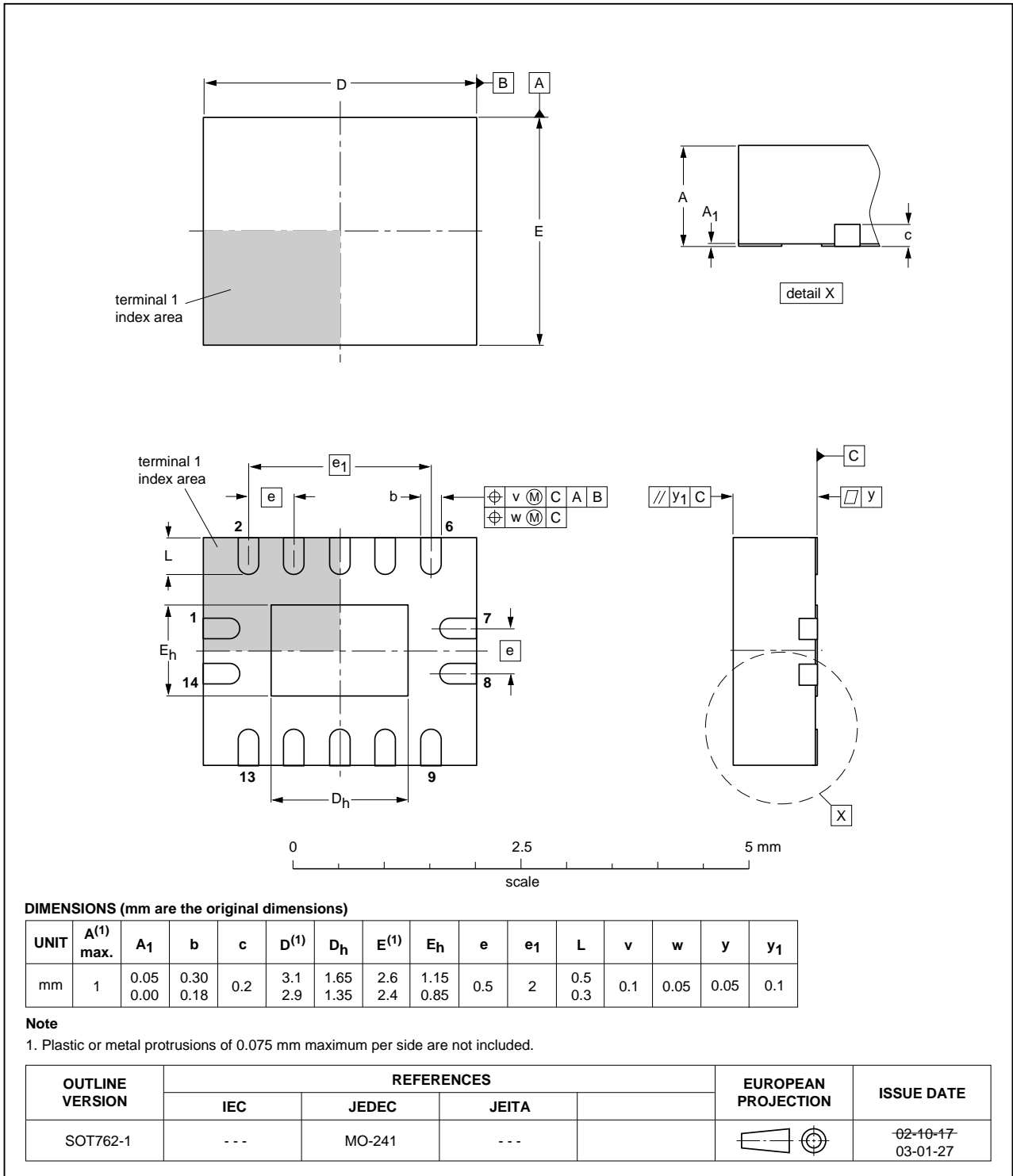


Fig 13. Package outline SOT762-1 (DHVQFN14)

## 13. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 14. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC74A v.7	20121120	Product data sheet	-	74LVC74A v.6
Modifications:	<ul style="list-style-type: none"> <li>• <a href="#">Table 6</a>, <a href="#">Table 7</a>, <a href="#">Table 8</a>, <a href="#">Table 9</a> and <a href="#">Table 10</a>: values added for lower voltage ranges.</li> </ul>			
74LVC74A v.6	20070604	Product data sheet	-	74LVC74A v.5
74LVC74A v.5	20070525	Product data sheet	-	74LVC74A v.4
74LVC74A v.4	20030526	Product specification	-	74LVC74A v.3
74LVC74A v.3	20020618	Product specification	-	74LVC74A v.2
74LVC74A v.2	19980617	Product specification	-	74LVC74A v.1
74LVC74A v.1	19980617	Product specification	-	-



## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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